

**Amendments to the Specification:**

Please amend the specification as follows:

Please replace paragraph starting at page 11, line 26 with the following rewritten paragraph:

Further, [[the]] it is preferable that the area occupied by said depressions 2 is in the range of 20 to 90 % of the total area of the member in a plan view observation of the predetermined are viewed from above the support portion.

Please replace paragraph starting at page 15, line 2 with the following rewritten paragraph:

The wafer support portion of a susceptor prepared by a step similar to Example 1 is subjected [[t]] to abrasion by means of a rotary grinder to obtain a susceptor formed with a silicon carbide (SiC) film having a surface roughness Ra of  $0.38\mu\text{m}$  on the top surfaces 1a of the salients. It is to be noted that the ratio of the area to said depressions is 60% while the surface roughness is equal to that in Example 2.